



# DEK NAA

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# DEK APC (All Purpose Clamping) Technical Specification

04/2017 Edition

### DEK All Purpose Clamping (APC)

#### Description

APC is a substrate clamping system which clamps the substrate flat (eliminating warpage) to enable good tooling contact. Subsequently if desired, the substrate is snugged and the top clamps retract from the substrate top surface to allow close to the edge printing and direct contact of the stencil to the board all the way to the board edges.

APC automatically adjusts for variation in board thickness, eliminating set-up requirements between production batches and compensating for any thickness variation within the batch. APC also has a compliant rear clamp, which automatically adjusts for out of parallel boards.

APC has three modes of operation. As all modes are software controlled via the program, there is no mechanical changing of parts or operator assistance needed to change modes. The three modes are:

- 1. Clamp- Standard Over The Top clamping (DEK standard foil system)
- 2. Snug– Clamp, Snug, Clamp Retract
- 3. Snug and Clamp Standard Over The Top clamping plus Snug functionality.

Available on the following transport system: Modular Rails. Compressed air supply min. 0.6Mpa (6bar), max. 0.8 Mpa (8bar), 5 litre/min required for APC

#### Function

The full APC clamp/unclamp sequence in Snug Mode is as follows,

#### **APC Clamp**

- Clamps pull substrate flat
- Snugger engages substrate
- Clamps withdraw from the substrate top surface and sit level with the substrate top surface.

#### **APC Unclamp**

- Snugger disengages substrate.
- Clamps raise, allowing the release of the substrate, then extend to wait for next board.

The Clamp and the Snug pressures are stored in the product file as they are Product Specific settings.



### DEK All Purpose Clamping (APC)

Substrate Handling	Specification
Rail Type	Modular Rails with Dual Speed Motors is standard with APC for all NeoHorizon
Minimum Substrate Size	03ix and 01ix models, and not available on any HTC transport system Host capability not affected by option
Maximum Substrate Size	Host capability not affected by option
Minimum Substrate Thickness	0.5mm*
Maximum Substrate Thickness	6.0mm
Maximum Substrate Warpage	Board Thickness + Warpage = < 6mm (also substrate rigidity in relation to snug force to overcome)
Maximum Substrate Weight	Host capability not affected by option
Minimum AWSM Width	562mm minimum stencil frame size required (using standard 30mm stencil supports)
Clamp Length	380mm
Clamp Modes	Clamp Snug Snug and Clamp
Clamp Force Setting	1.5 to 5 bar
Snugger Length	356mm
Snug Force Setting	20 to 60 Newtons
Clamp Overhang on Substrate	1.5mm (Maximum per clamped edge)
Transport Direction	Host capability not affected by option
Underside Edge Support Thickness	3.5mm (Maximum per clamped edge)
Underside Edge Support Length	Standard 500mm
Component Under Clearance	Host capability not affected by option
ESD Compatibility	Yes
Substrate Edge Straightness	+/- 0.05mm
Substrate Edge Parallelism	+/- 0.5mm
Board Aspect Ratio	Host capability not affected by option
Transport Height	Host capability not affected by option
Core Cycle Time	8 seconds** for both NeoHorizon 03ix and 01ix when using Over the Top Clamping Mode (standard foils)

\* Theoretical minimum, in practice this is dictated by the ability of the substrate to withstand a snugging force and the belt compression of the Modular Rail system. Vacuum tooling is recommended for products 1mm in thickness or less.

\*\* Using the Snug or Snug & Clamp mode will incur an extra time penalty of up to one second, as measured in seconds using the ASM defined core cycle time test parameters, for details contact the Product Manager.



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## Notes



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